





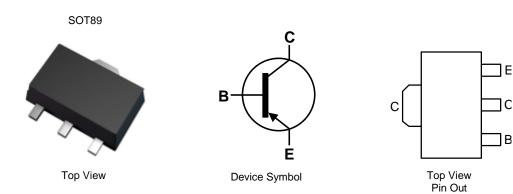
400V PNP HIGH VOLTAGE TRANSISTOR IN SOT89

Features

- BV_{CEO} > -400V
- I_C = -200mA High Continuous Current
- I_{CM} = -500mA Peak Pulse Current
- Excellent h_{FE} Characteristics up to -100mA
- Low Saturation Voltage V_{CE(sat)} < -200mV @ -20mA
- Complementary NPN Type: FCX458
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT89
- Case Material: Molded Plastic. "Green" Molding Compound.
 UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.05 grams (Approximate)



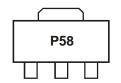
Ordering Information (Note 4)

| h | | | | | | |
|---|----------|------------|---------|--------------------|-----------------|-------------------|
| | Product | Compliance | Marking | Reel Size (inches) | Tape Width (mm) | Quantity per Reel |
| | FCX558TA | AEC-Q101 | P58 | 7 | 12 | 1,000 |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http"//www.diodes.com/products/packages.html.

Marking Information



P58 = Product Type Marking Code



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Limit | Unit |
|------------------------------|------------------|-------|------|
| Collector-Base Voltage | V_{CBO} | -400 | V |
| Collector-Emitter Voltage | V _{CEO} | -400 | V |
| Emitter-Base Voltage | V_{EBO} | -7 | V |
| Continuous Collector Current | Ic | -200 | mA |
| Peak Pulse Current | I _{CM} | -500 | mA |

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit | | |
|---|-----------------------------------|------------------|------|------|--|
| | (Note 5) | P _D | 0.7 | W | |
| Bower Discination | (Note 6) | | 1.0 | | |
| Power Dissipation | (Note 7) | | 1.5 | | |
| | (Note 8) | | 2.0 | | |
| | (Note 5) | R _{ӨЈА} | 178 | °C/W | |
| Thermal Resistance, Junction to Ambient Air | (Note 6) | | 125 | | |
| Thermal Resistance, Junction to Ambient Air | (Note 7) | | 83 | | |
| | (Note 8) | | 60 | | |
| Thermal Resistance, Junction to Lead (Note 9) | | $R_{	heta JL}$ | 22 | | |
| Operating and Storage Temperature Range | T _J , T _{STG} | -65 to +150 | °C | | |

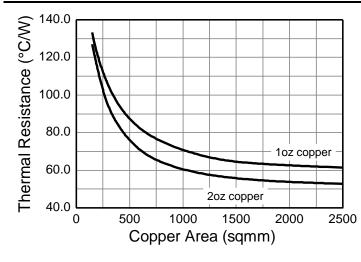
ESD Ratings (Note 10)

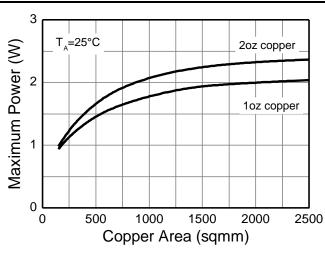
| Characteristic | Symbol | Value | Unit | JEDEC Class |
|--|---------|-------|------|-------------|
| Electrostatic Discharge - Human Body Model | ESD HBM | 4,000 | ٧ | 3A |
| Electrostatic Discharge - Machine Model | ESD MM | 400 | V | С |

Notes:

- 5. For a device mounted with the exposed collector pad on minimum recommended pad layout (MRP) 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
- 6. Same as Note 5, except the device is mounted with the exposed collector pad on 15mm x 15mm 1oz copper.
- 7. Same as Note 5, except the device is mounted with the exposed collector pad on 25mm x 25mm 1oz copper.
- 8. Same as Note 5, except the device is mounted with the exposed collector pad on 50mm x 50mm 1oz copper.
- 9. Thermal resistance from junction to solder-point (on the exposed collector pad).
- 10. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

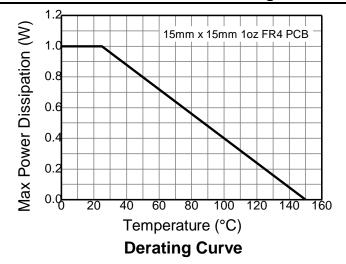
Thermal Characteristics and Derating Information

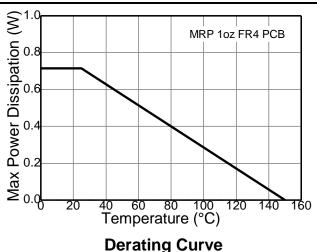


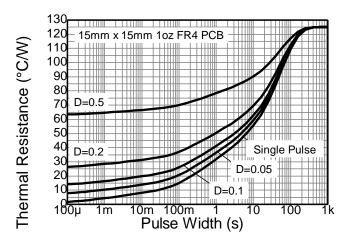


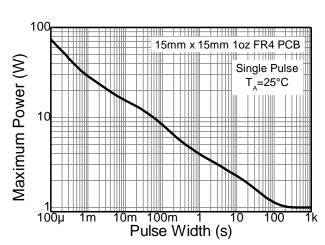


Thermal Characteristics and Derating Information (cont.)



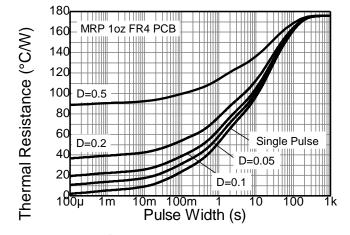


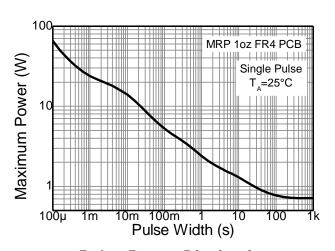




Transient Thermal Impedance

Pulse Power Dissipation

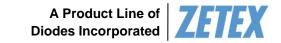




Transient Thermal Impedance

Pulse Power Dissipation





Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

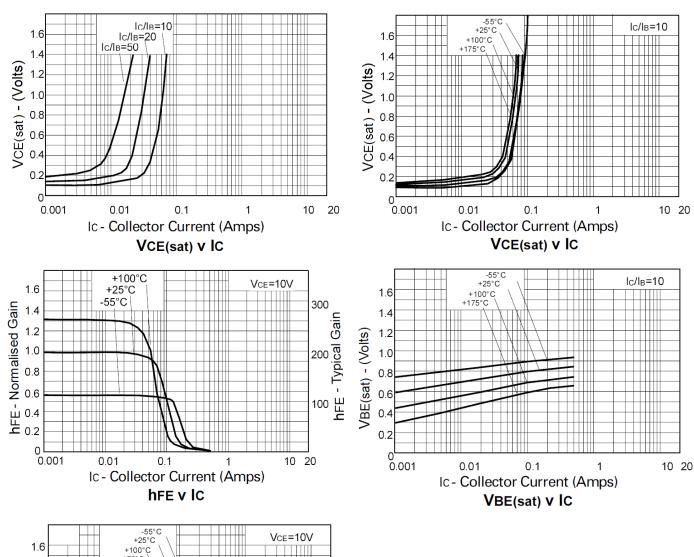
| Characteristic | Symbol | Min | Тур. | Max | Unit | Test Condition |
|--|-------------------------------------|------------------|-------------|---------------|------|--|
| Collector-Base Breakdown Voltage | BV _{CBO} | -400 | - | - | V | $I_{C} = -100 \mu A$ |
| Collector-Emitter Breakdown Voltage (Note 11) | BV _{CEO} | -400 | - | - | V | $I_C = -1mA$ |
| Emitter-Base Breakdown Voltage | BV _{EBO} | -7 | - | - | V | $I_E = -100 \mu A$ |
| Collector Cutoff Current | I _{CBO} | = | <1 | -100 | nA | V _{CB} = -320V |
| Emitter Cutoff Current | I _{EBO} | = | <1 | -100 | nA | $V_{EB} = -5V$ |
| Emitter Cutoff Current | I _{CES} | = | <1 | -100 | nA | V _{CES} = -320V |
| DC Current Transfer Static Ratio (Note 11) | h _{FE} | 100 100 15 | - - - | - 300 - | - | I _C = -1mA, V _{CE} = -10V I _C = -50mA, V _{CE} = -10V I _C = -100mA, V _{CE} = -10V |
| Collector-Emitter Saturation Voltage (Note 11) | V _{CE(sat)} | | - | -0.2 -0.5 | V | I _C = -20mA, I _B = -2mA I _C = -50mA, I _B = -6mA |
| Base-Emitter Saturation Voltage (Note 11) | V _{BE(sat)} | - | - | -0.9 | V | $I_C = -50 \text{mA}, I_B = -5 \text{mA}$ |
| Base-Emitter Turn-on Voltage (Note 11) | V _{BE(on)} | = | - | -0.9 | V | $I_C = -50 \text{mA}, V_{CE} = -10 \text{V}$ |
| Transitional Frequency | f⊤ | 50 | - | - | MHz | $I_E = -10 \text{mA}, V_{CE} = -20 \text{V}$ f = 20 MHz |
| Output Capacitance | C_{obo} | - | - | 5 | pF | $V_{CB} = -20V, f = 1MHz,$ |
| Switching Times | t _{on} t _{off} | _ | 95 1600 | - | nS | $I_C = -50$ mA, $V_C = -100$ V $I_{B1} = -5$ mA, $I_{B2} = -10$ mA |

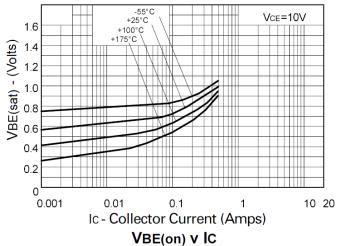
Note:

11. Measured under pulsed conditions. Pulse width ≤ 300µs. Duty cycle ≤ 2%.



Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

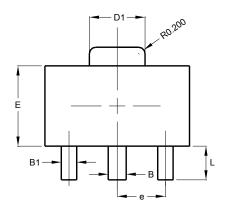


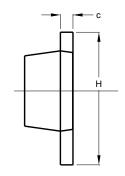


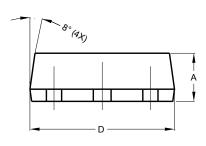


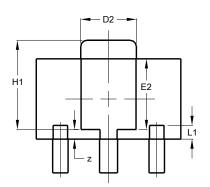
Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.





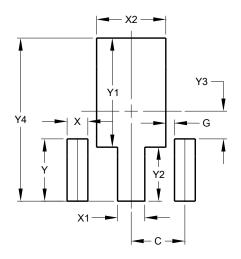




| SOT89 | | | | | |
|----------------------|-----------|------|-------|--|--|
| Dim | Min | Max | Тур | | |
| Α | 1.40 | 1.60 | 1.50 | | |
| В | 0.50 | 0.62 | 0.56 | | |
| B1 | 0.42 | 0.54 | 0.48 | | |
| C | 0.35 | 0.43 | 0.38 | | |
| D | 4.40 | 4.60 | 4.50 | | |
| D1 | 1.62 | 1.83 | 1.733 | | |
| D2 | 1.61 | 1.81 | 1.71 | | |
| Е | 2.40 | 2.60 | 2.50 | | |
| E2 | 2.05 | 2.35 | 2.20 | | |
| е | - | 1.50 | | | |
| Н | 3.95 | 4.25 | 4.10 | | |
| H1 | 2.63 | 2.93 | 2.78 | | |
| L | 0.90 | 1.20 | 1.05 | | |
| L1 | 0.427 REF | | | | |
| Z | 0.30 REF | | | | |
| All Dimensions in mm | | | | | |

Suggested Pad Layout

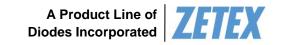
Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



| Dimensions | value | | |
|------------|---------|--|--|
| Dimensions | (in mm) | | |
| С | 1.500 | | |
| G | 0.244 | | |
| X | 0.580 | | |
| X1 | 0.760 | | |
| X2 | 1.933 | | |
| Υ | 1.730 | | |
| Y1 | 3.030 | | |
| Y2 | 1.500 | | |
| Y3 | 0.770 | | |
| Y4 | 4.530 | | |
| | | | |

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.





December 2014

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